



Test Items	Test Method	Test Condition	Unit	Typical Value
Thermal Conductivity	ASTM-D5470	Dielectric layer	W/(m·K)	3.0
Thermal Resistance	ASTM-D5470	Dielectric layer	K·cm <sup>2</sup> /W	0.34
Tg	IPC-TM-650 2.4.25D	DSC	°C	155
Td	IPC-TM-650 2.4.24.6	5% Wt. loss	°C	400
Thermal Stress	IPC-TM-650 2.4.13.1	288°C, solder float	min	30
CTE(Z-axis)	IPC-TM-650 2.4.24	Before Tg	ppm/°C	20
	IPC-TM-650 2.4.24	After Tg	ppm/°C	31
	IPC-TM-650 2.4.24	50-260°C	%	0.48
Volume Resistivity	IPC-TM-650 2.5.17.1	C-96/35/90	N -cm	10 <sup>8</sup>
Surface Resistivity	IPC-TM-650 2.5.17.1	C-96/35/90	N	10 <sup>8</sup>
Dielectric Breakdown	IPC-TM-650 2.5.6	D-48/50+D-0.5/23	kV	5.0
Hi-pot Test	GB/T 31988	DC	V	4000
		AC	V	3000
Peel Strength(1oz)	IPC-TM-650 2.4.8	288°C/10s	N/mm	1.15
Flammability	UL94	C-48/23/50	Rating	V-0
MOT	UL	A	°C	130
CTI	IEC60112	A	Rating	PLC 0

	Material	Thickness
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